



Material Content Data Sheet



Sales Product Name		IPU60R1K0CE		Issued		2. August 2018		
MA#		MA001507198						
Package		PG-TO251-3-345		Weight*		385.53 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.144	0.56	0.56	5560	5560
leadframe	non noble metal	iron	7439-89-6	0.209	0.05		541	
	inorganic material	phosphorus	7723-14-0	0.063	0.02		162	
	non noble metal	copper	7440-50-8	208.238	54.01	54.08	540130	540833
wire	non noble metal	aluminium	7429-90-5	4.505	1.17	1.17	11685	11685
encapsulation	organic material	carbon black	1333-86-4	0.681	0.18		1766	
	plastics	epoxy resin	-	18.382	4.77		47680	
	inorganic material	silicondioxide	60676-86-0	117.101	30.37	35.32	303738	353184
leadfinish	non noble metal	tin	7440-31-5	7.055	1.83	1.83	18299	18299
solder	noble metal	silver	7440-22-4	0.056	0.01		146	
	non noble metal	tin	7440-31-5	0.045	0.01		116	
	non noble metal	lead	7439-92-1	2.144	0.56	0.58	5562	5824
heatspreader	non noble metal	iron	7439-89-6	0.025	0.01		65	
	inorganic material	phosphorus	7723-14-0	0.007	0.00		19	
	non noble metal	copper	7440-50-8	24.879	6.45	6.46	64531	64615
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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